Abstracts

Design and analysis of low cost IC package solution for 10 Gbit/s applications

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Low cost IC package solution for 10 Gbit/s applications will be presented. The RF-LGA, laminate based CSP will be used. Design and analysis, in the frequency and time domains, of the RF-LGA is demonstrated. Results show that RF-LGA package, with wirebond technology, could achieve the required electrical performance for 10 Gbit/s applications.

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